



DB1 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 21.87%	Copper (Cu)	7440-50-8	93.990	99.98	218,622.1
	Phosphorus (P)	7723-14-0	0.0009	0.0010	2.1
	Arsenic (As)	7440-38-2	0.0009	0.0010	2.1
	Tin (Sn)	7440-31-5	0.0009	0.0010	2.1
	Oxygen (O)	7782-44-7	0.0005	0.0005	1.2
	Sulfur (S)	7704-34-9	0.0113	0.0120	26.3
	Iron (Fe)	7439-89-6	0.0006	0.0006	1.4
	Nickel (Ni)	7440-02-0	0.0003	0.0003	0.7
	Bismuth (Bi)	7440-69-9	0.0019	0.0020	4.4
	Antimony (Sb)	1309-64-4	0.0019	0.0020	4.4
	Lead (Pb)	7439-92-1	0.0005	0.0005	1.2
	Zinc (Zn)	7440-66-6	0.0003	0.0003	0.7
	Total		94.01		
Solder Wafer 1.02%	Lead (Pb)	7439-92-1	4.06	92.48	9,443.6
	Tin (Sn)	7440-31-5	0.22	5.01	511.7
	Silver (Ag)	7440-22-4	0.11	2.51	255.9
	Total		4.39		
Chip 0.84%	Silicon (Si)	7440-21-3	3.43	95.40	7,978.2
	Lead (Pb)	7439-92-1	0.17	4.60	395.4
	Total		3.60		
Molding 76.06%	Epoxy	38891-59-7	327.00	100.00	760,606.6
	Total		327.00		
Plating 0.21%	Tin (Sn)	7440-31-5	0.92	100.00	2,139.9
	Total		0.92		
	Total mass (mg)		429.92		